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Patent
Attorney's Docket No. 015290-506

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of) **BOX AF**
Ting CHIEN et al.)
Application No.: 09/820,692) **Group Art Unit: 1765**
Filed: March 30, 2001) **Examiner: K.C. Chen**
For: **PLASMA ETCHING OF DIELECTRIC LAYER**) **Confirmation No. 5245**
WITH SELECTIVITY TO STOP LAYER)

REQUEST FOR RECONSIDERATION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Reconsideration of the Final Official Action dated August 7, 2002 is respectfully requested.

REMARKS

Claims 1-25 are pending in the application for the Examiner's review and consideration.

Claims 23-25 were rejected under 35 U.S.C. § 112, first paragraph, for allegedly containing subject matter not described in the specification. This rejection is respectfully traversed for the following reasons. Claim 23 is directed to an *etchant gas* that is hydrogen-free. Claim 24 is directed to an etchant gas consisting essentially of a *hydrogen-free fluorocarbon gas*, an oxygen-containing gas and a optional carrier gas. Claim 25 is

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